

HOT TEST HANDLER TH282X



Overview

This machine is applicable for QFP, TSSOP, BGA, or CSP package device supplied by plastic tray and mounts 1- 4 devices on the measurement unit under high temperature condition and then classifies them based on measurement results and sort them in the specified tray.

Features

1. Applicable many type package by easy parts exchange.
2. Correct contact with test socket, using unique positioning mechanism.
3. Transfer mechanism never damages package, lead, ball and any bump.
4. Easy interfacing with any Testers.
5. High performance, using double picking up arm.
6. Easy operation with LCD touch panel switch.
7. Cover has the solenoid lock for safety operation

Specification

1. Applicable package
QFP, TSSOP, BGA, CSP package in a tray
2. Applicable Tray size
JEDEC Standard tray
322.6mm(L) x 135.9mm(W) x 7.62mm(T)
3. Test Sites
4 hot or ambient test site
Hot temperature : 80-125 centigrade degrees
+/- 5 degrees
4. Loader / Unloader
Auto-Loader : 40 JEDEC standard trays
stock (250mm height)
Auto-Unloader :
Sort 1,2 : 40 JEDEC standard trays stock
(250mm height)
Sort 3,4 : each one tray

Through put

- UPH : 3100 (4 devices simultaneously)
(exchange 0.5sec + testing time 4.0sec)
UPH : 2400 (2 devices simultaneously)
(exchange 0.5sec + testing time 2.0sec)



Others

1. Option
Change kit for Tray except for JEDEC size
Change kit for other package size
Additional ionizers protecting ESD
Tester Head stand
Interface with external computer
Data input by a bar code reader
Operation with Windows-PC
(Easy data edit & Alarm data logging)
2. Others
Low Jamming rate
ESD protection < 50V
MTBA > 90minutes
Signal tower with 3 colors
3. Dimensions
1310mm(W) x 1655mm(D) x 1515mm(H)

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